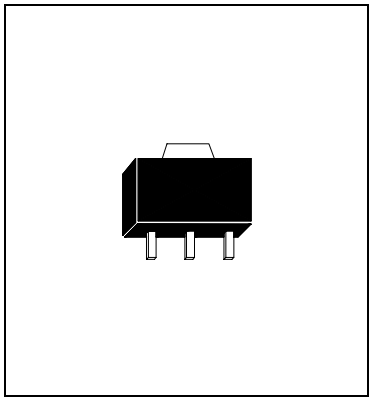
HM94

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HM94 is designed for application requires high voltage.

Features

- High voltage: VCEO=400V(min) at IC=1mA
- High current gain: IC=300mA at 25°C
- Complementary with HM44

Absolute Maximum Ratings

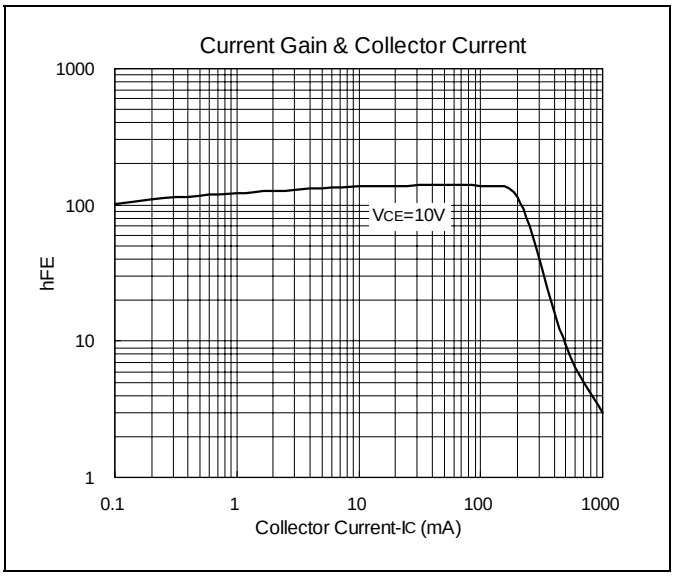
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -400 V
  VCEO Collector to Emitter Voltage ..... -400 V
  VEBO Emitter to Base Voltage ..... -6 V
  IC Collector Current ..... -500 mA

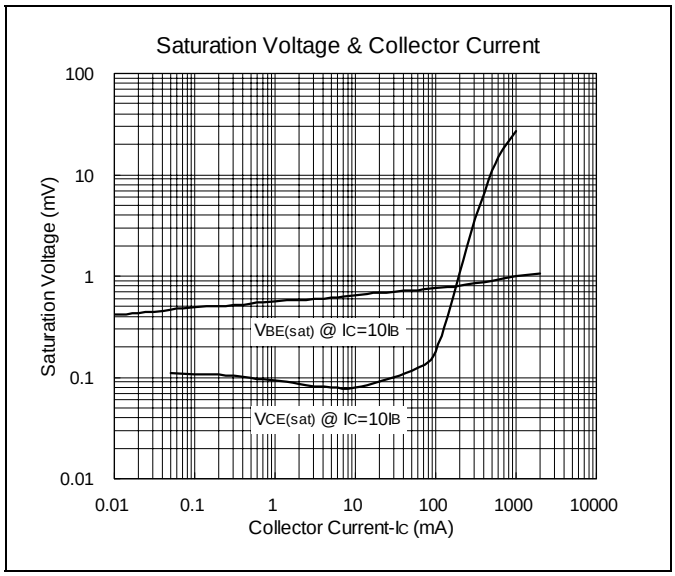
Characteristics (Ta=25°C)

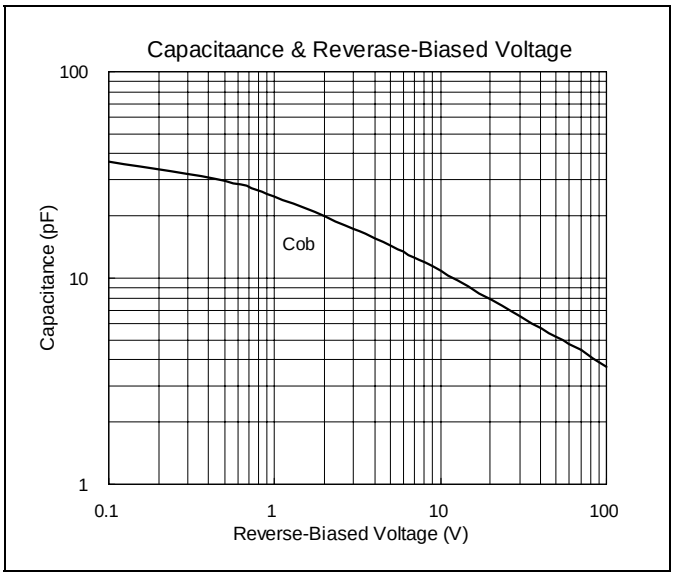
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-400	-	-	V	IC=-100uA
BVCEO	-400	-	-	V	IC=-1mA
BVEBO	6	-	-	V	IE=-10uA
ICBO	-	-	-100	nA	VCB=-400V
IEBO	-	-	-100	nA	VEB=-6V
ICES	-	-	-500	nA	VCE=-400V, VBE=0
*VCE(sat)1	-	-	-350	mV	IC=-1mA, IB=-0.1mA
*VCE(sat)2	-	-	-500	mV	IC=-10mA, IB=-1mA
*VCE(sat)3	-	-	-750	mV	IC=-50mA, IB=-5mA
*VBE(sat)	-	-	-750	mV	IC=-10mA, IB=-1mA
*hFE1	40	-	-		VCE=-10V, IC=-1mA
*hFE2	50	-	300		VCE=-10V, IC=-10mA
*hFE3	45	-	-		VCE=-10V, IC=-50mA
*hFE4	40	-	-		VCE=-10V, IC=-100mA

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

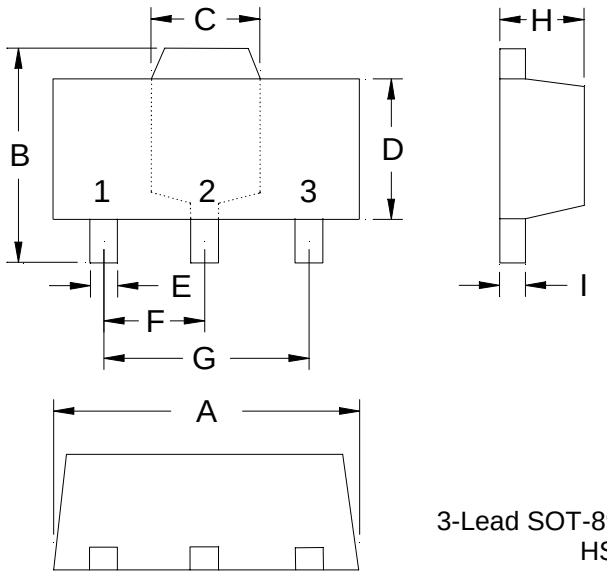
Characteristics Curve



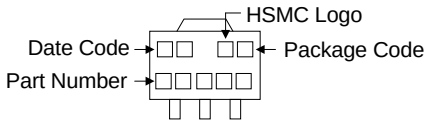




SOT-89 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-89 Plastic Surface Mounted Package
HSMC Package Code : M

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
  Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1 :** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2 :** No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel : 886-3-5977061 Fax : 886-3-5979220